



## 2 TECHNOLOGY & MARKET ANALYSTS | PACKAGE & ASSEMBLY

With offices in France, Germany, Japan, Greater China and the U.S.A, Yole Développement (Yole) the « More than Moore » company, provides market research, technology analysis, strategic consulting, media services and financial services to a worldwide customer base.

Covering emerging and disruptive silicon and micro manufacturing markets, the group supports companies, investors and R&D organizations by delivering comprehensive analysis that helps them understand the markets and technology trends critical to their business.

### JOB DESCRIPTION

Our company proposes immediate openings for two Market and Technology Analyst positions to strengthen our Package & Assembly activities by performing market, technology, and strategic analysis.

One position based in France (Headquarter) and the other in Asia or US.

You will work in close collaboration within the S & S (Semiconductors & Software) team as well as take part in the projects of the different Business Units (Power / Compounds, MEMS & Sensors, MedTech, LED / Display).

Regular business trips (Europe, USA, Asia) are expected.

### YOUR RESPONSABILITIES

As a Package & Assembly Expert, you will be responsible to :

- Execute technical, marketing, and strategic analysis
- Oversee technology and industry insights from Package & Assembly market trends, from devices to package type (3D, fan-out, flip chip, embedded die...)
- Understand the impact of the emergence of new or improved technologies in various applications
- Execute projects within a given timeframe and budget.
- Participate in the establishment and structuration of commercial offers
- Create and manage long-term relationships with customers
- Collect information and promote our activities in conferences and dedicated trade-shows
- Give presentations at international conferences and workshops.

### EDUCATION / EXPERIENCE

- Experience (3-10 years) in the packaging field
- Strong knowledge of the Packaging technologies: 3D, System In Package, flip chip, fan out, wafer-level-packaging as well as advanced substrate and standard packaging platforms.
- University Degree (Master, Engineer, PhD) in a semiconductor-related field is mandatory
- Strong interest in product market entry / applications (marketing, strategic planning, etc.).
- Required English level: minimum CECR - CI / TOEIC 900.
- Proficiency in French is a plus but not mandatory

*Please send your latest CV & cover letter to [recruiting@yole.fr](mailto:recruiting@yole.fr)*

